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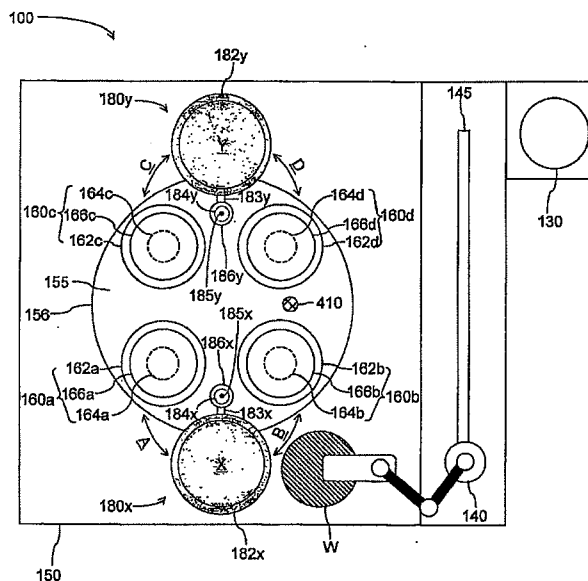
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(54) Title: APPARATUS AND METHOD FOR POLISHING SEMICONDUCTOR WAFERS USING ONE OR MORE PIVOTABLE LOAD-AND-UNLOAD CUPS



(57) Abstract: An apparatus and method for polishing objects, such as semiconductor wafers, utilizes one or more pivotable load-and-unload cups (182) to transfer the objects to and/or from one or more object carriers (160) to polish the objects. Each pivotable load-and-unload cup may be configured to transfer the objects to and/or from a single object carrier. Alternatively, each pivotable load-and-unload cup may be configured to transfer the objects to and/or from two object carriers. The pivotable load-and-unload cups may be configured to be pivoted about one or more pivoting points over at least one polishing surface, such as a polishing pad surface.



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